Functional Diagram



Ordering Information

Part Number	Junction Temperature Range	Package	Pb-Free
MIC58P42YN	–40°C to +85°C	18-Pin Plastic DIP	\checkmark
MIC58P42YV	-40°C to +85°C	20-Pin PLCC	\checkmark
MIC58P42YWM	-40°C to +85°C	18-Pin Wide SOIC	\checkmark

Pin Configuration



Typical Input Circuits

o Vss



SUB

o v₅s

Pin Description

Pin Number DIP & SOIC	Pin Number PLCC	Pin Name	Pin Function	
1, 9	1, 11	V _{EE}	Substrate. Most Negative voltage in the system connects here.	
2	2	CLOCK	Serial Data Clock. A CLEAR input must also be clocked into the latches.	
3	3	SERIAL DATA IN	Serial Data Input pin.	
4	5	V _{SS}	Logic reference (Ground) pin.	
5	6	V _{DD}	Logic Positive Supply voltage.	
6	7	SERIAL DATA OUT	Serial Data Output pin. (Flow–through).	
7	9	STROBE	Output Strobe pin. Loads output latches when high. Strobe is needed to clear latch.	
8	10	OUTPUT ENABLE/RESET	When Low, Outputs are active. When High, device is reset from a fault condition.	
10	12	К	Transient suppression diode's cathode common pin.	
11 – 18	13 – 20	OUT _N	Open Collector outputs 8 through 1.	

Absolute Maximum Ratings⁽¹⁾

Output Voltage	+80V
Output Voltage, V _{CE(SUS)} ⁽³⁾	+50V
Logic Supply Voltage Range (V _{DD})	4.5V to 15V
V _{DD} with reference to V _{EE}	25V
Emitter Supply Voltage (Substrate) (V _{EE}).	–20V
Input Voltage Range (VIN)	0.3V to V _{DD} +0.3V
Operating Temperature Range (T _A)	–65°C to +125°C
Storage Temperature Range (T _S)	60°C to +150°C
ESD Rating ⁽⁴⁾	ESD Sensitive

Operating Ratings⁽²⁾

Package Power Dissipation, P _D	
MIC58P42YN	1.82W
Derate above $T_A = +25^{\circ}C$	18mW/°C
MIC58P42YV	1.4W
Derate above T _A = +25°C	14mW/°C
MIC58P42YWM	1.2W
Derate above $T_A = +25^{\circ}C$	12mW/°C
Operating Temperature Range (T _A)	40°C to +85°C

Electrical Characteristics⁽⁵⁾

 T_{A} = 25°C, V_{DD} = 5V; V_{SS} = V_{EE} = 0V, unless otherwise noted.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units	
	Output Leskens Ourrent	$V_{OUT} = 80V$			50	μA	
ICEX	Output Leakage Current	$V_{OUT} = 80V, T_A = +70^{\circ}C$			100		
		I _{OUT} = 100mA		0.9	1.1		
V _{CE(SAT)}	Voltage	I _{OUT} = 200mA		1.1	1.3	V	
		I _{OUT} = 350mA		1.3	1.6		
V _{CE(SUS)}	Collector-Emitter Sustaining Voltage	I _{OUT} = 350mA, L = 2mH	50			V	
V _{IN(0)}	Input Voltage (Low)				1.0		
		$V_{DD} = 12V$		10.5		V	
V _{IN(1)}	Input Voltage (High)	$V_{DD} = 10V$		8.5		v	
		V _{DD} = 5.0V, Note 6		3.5			
		$V_{DD} = 12V$	50	200			
R _{IN}	Input Resistance	$V_{DD} = 10V$	50	300		kΩ	
		$V_{DD} = 5.0 V$	50	600			
		All Drivers ON, V _{DD} = 12V		6.4	10.0		
I _{DD(ON)}		All Drivers ON, $V_{DD} = 10V$		6.0	9.0		
		All Drivers ON, $V_{DD} = 5.0V$		4.6	7.5		
		One Driver ON, All others OFF, $V_{DD} = 12V$		3.1	4.5		
I _{DD(1 ON)}	Supply Current	One Driver ON, All others OFF, V _{DD} = 10V		2.9	4.5	mA	
		One Driver ON, All others OFF, V_{DD} = 5.0V		2.3	3.6	3.6	
		All Drivers OFF, V _{DD} = 12V		2.6	4.2		
I _{DD(OFF)}		All Drivers OFF, V _{DD} = 10V		2.4	3.6		
		All Drivers OFF, V _{DD} = 5.0V		1.9	3.0		

Notes:

2. The device is not guaranteed to function outside its operating ratings.

- 3. For inductive load applications.
- 4. Devices are ESD sensitive. Handling precautions are recommended. Human body model, $1.5k\Omega$ in series with 100pF.
- 5. Specification for packaged product only.
- 6. Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to insure a minimum logic "1".

^{1.} Exceeding the absolute maximum ratings may damage the device.

Electrical Characteristics (Continued)

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
I _R	Clamp Diode Leakage Current	V _R = 80V			50	μA
V _F	Clamp Diode Forward Voltage	I _F = 350mA		1.7	2.0	V
I _{LIM}	Output Current Shutdown Threshold			500		mA
V _{SU}	Start Up Voltage	Note 7	3.5	4.0	4.5	V
V _{DD MIN}	Minimum Supply (V _{DD})		3.0	3.5	4.0	V
	Thermal Shutdown			165		°C
	Thermal Shutdown Hysteresis			10		°C

Note:

7. Undervoltage Lockout is guaranteed to release device at no more than 4.5V, and disable the device at no less than 3.0V.

Timing Diagram



Timing Conditions

(T _A	= +25°C, Logic Levels are V_{DD} and V_{SS}), V_{DD} = 5V	
Α.	Typical Data Active Time Before Clock Pulse (Data Set-Up Time)	75ns
В.	Minimum Data Active Time After Clock Pulse (Data Hold Time).	75ns
C.	Minimum Data Pulse Width	. 150ns
D.	Minimum Clock Pulse Width	. 150ns
Ε.	Minimum Time Between Clock Activation and Strobe	. 300ns
F.	Minimum Strobe Pulse Width	. 100ns
G.	Typical Time Between Strobe Activation and Output Transition	. 500ns

SERIAL DATA present at the input is transferred to the shift register on the logic "0" to logic "1" transition of the CLOCK input pulse. On succeeding CLOCK pulses, the registers shift data information towards the SERIAL DATA OUTPUT. The SERIAL DATA must appear at the input prior to the rising edge of the CLOCK input waveform.

Information present at any register is transferred to its respective latch when the STROBE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the STROBE is held high. Applications where the latches are bypassed (STROBE tied high) will require that the ENABLE input be high to prevent invalid output states.

When the ENABLE input is high, all of the output buffers are disabled (OFF) without affecting information stored in the latches or shift register. With the ENABLE input low, the outputs are controlled by the state of the latches. A positive OUTPUT ENABLE/ RESET pulse resets the output after a current shutdown fault. Thermal limit faults are not latched and require no reset pulse.

MIC58P42 Truth Table

Serial	Clock Input	Clock	Clock	Shift Register Contents	Serial	Strobe	Latch Contents	Output	Output Contents
Data Input		l ₁ l ₂ l ₃ l ₈	Data Output	Input	l ₁ l ₂ l ₃ l ₈	Enable	I ₁ I ₂ I ₃ I ₈		
Н	Ч	$H R_1 R_2 \dots R_7$	R ₇						
L	Г	L R ₁ R ₂ R ₇	R ₇						
Х	l	$R_1 \ R_2 \ R_3 \ \dots \ R_8$	R ₈						
	Г	0 0 0 0	L						
		X X X X	Х	L	R ₁ R ₂ R ₃ R ₈				
		$P_1 P_2 P_3 \dots P_8$	P ₈	Н	$P_1 P_2 P_3 \dots P_8$	L	$P_1 P_2 P_3 \dots P_8$		
					X X X X	Н	н н н н		

L = Low Level Logic

H = High Level Logic

X = Irrelevant

P = Present State

R = Previous State

O = Output OFF

Typical Characteristics













Maximum Allowable Duty Cycle, Plastic DIP

$V_{DD} = 5.0V$

Number of Outputs ON (Jour = 200mA	Max. Allowable Duty Cycle at Ambient Temperatures						
$V_{DD} = 5.0V)$	25°C	40°C	50°C	60°C	70°C		
8	85%	72%	64%	55%	46%		
7	97%	82%	73%	63%	53%		
6	100%	96%	85%	73%	62%		
5	100%	100%	100%	88%	75%		
4	100%	100%	100%	100%	93%		
3	100%	100%	100%	100%	100%		
2	100%	100%	100%	100%	100%		
1	100%	100%	100%	100%	100%		

 $V_{DD} = 12V$

Number of Outputs ON (I _{OUT} = 200mA V _{DD} = 12V)	Max. Allowable Duty Cycle at Ambient Temperatures						
	25°C	40°C	50°C	60°C	70°C		
8	80%	68%	60%	52%	44%		
7	91%	77%	68%	59%	50%		
6	100%	90%	79%	69%	58%		
5	100%	100%	95%	82%	69%		
4	100%	100%	100%	100%	86%		
3	100%	100%	100%	100%	100%		
2	100%	100%	100%	100%	100%		
1	100%	100%	100%	100%	100%		





Note:

8. Package information is correct as of the publication date. For updates and most current information, go to www.micrel.com.

Package Information and Recommended Landing Pattern⁽⁸⁾ Continued



18-Pin DIP (N)

Package Information and Recommended Landing Pattern⁽⁸⁾ Continued



20-Pin PLCC (V)

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